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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/609,499	07/01/2003	Jong-Jin Lee	053933-5046	1723	
9629 7	590 12/21/2004		EXAMINER		
MORGAN LEWIS & BOCKIUS LLP			HA, NATHAN W		
WASHINGTON, DC 20004			ART UNIT	PAPER NUMBER	
			2814		
•			DATE MAILED: 12/21/2004		

Please find below and/or attached an Office communication concerning this application or proceeding.

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		Applicati	on No.	Applicant(s)				
Office Action Summary		10/609,4	99	LEE ET AL.				
		Examine	1	Art Unit				
		Nathan W	. Ha	2814				
Period fo	The MAILING DATE of this communic	ation appears on th	e cover sheet with the d	orrespondence addi	ess			
	ORTENED STATUTORY PERIOD FO	AD DEDI V IS SET T	O EXPIRE 3 MONTH	S) FROM				
THE - External after of the control	MAILING DATE OF THIS COMMUNIC insions of time may be available under the provisions of SIX (6) MONTHS from the mailing date of this communication of the properties of the provision of period for reply specified above, the maximum stature to reply within the set or extended period for reply we reply received by the Office later than three months after the patent term adjustment. See 37 CFR 1.704(b).	CATION. f 37 CFR 1.136(a). In no ev nication. days, a reply within the startutory period will apply and will, by statute, cause the ap	ent, however, may a reply be tire tutory minimum of thirty (30) day fill expire SIX (6) MONTHS from blication to become ABANDONE	nely filed s will be considered timely. the mailing date of this com D (35 U.S.C. § 133).	munication.			
Status								
1)[🛛	Responsive to communication(s) filed	on 30 November 2	004.					
· —	This action is FINAL . 2b)⊠ This action is non-final.							
3)□								
Disposit	ion of Claims							
4)🖂	Claim(s) 1-11 is/are pending in the ap	plication.						
	4a) Of the above claim(s) <u>1-6</u> is/are withdrawn from consideration.							
5)	Claim(s) is/are allowed.							
6)🖾	☑ Claim(s) <u>7-11</u> is/are rejected.							
7)	Claim(s) is/are objected to.							
8)	Claim(s) are subject to restricti	ion and/or election r	equirement.					
Applicat	ion Papers							
9)[The specification is objected to by the	Examiner.						
10)	10) The drawing(s) filed on is/are: a) accepted or b) objected to by the Examiner.							
	Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).							
	Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).							
11)[The oath or declaration is objected to	by the Examiner. N	ote the attached Office	Action or form PTC)-152.			
Priority	under 35 U.S.C. § 119							
•	Acknowledgment is made of a claim for	or foreian priority un	der 35 U.S.C. § 119(a)-(d) or (f).				
			•	, (-, - (,				
/	1.⊠ Certified copies of the priority d	locuments have bee	en received.					
	2. Certified copies of the priority d			ion No				
	3. Copies of the certified copies o				tage			
	application from the Internation							
* ;	See the attached detailed Office action	for a list of the cert	ified copies not receive	ed.				
					•			
Attachmei	nt(s)							
	ce of References Cited (PTO-892)		4) Interview Summary	(PTO-413)				
2) Noti	ce of Draftsperson's Patent Drawing Review (PT		Paper No(s)/Mail D	ate	450)			
	rmation Disclosure Statement(s) (PTO-1449 or Fer No(s)/Mail Date	PTO/SB/08)	5) Notice of Informal I 6) Other:	ratent Application (PTO-	152)			

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DETAILED ACTION

Election/Restrictions

1. Applicant's election of Group I, claims 7-11 in the reply filed on 11/30/04 is acknowledged. Because applicant did not distinctly and specifically point out the supposed errors in the restriction requirement, the election has been treated as an election without traverse (MPEP § 818.03(a)). Therefore, claims 1-6 have been withdrawn.

Specification

2. Applicant is reminded of the proper language and format for an abstract of the disclosure.

The abstract should be in narrative form and generally limited to a single paragraph on a separate sheet within the range of 50 to 150 words. It is important that **the abstract not exceed 150 words** in length since the space provided for the abstract on the computer tape used by the printer is limited. The form and legal phraseology often used in patent claims, such as "means" and "said," should be avoided. The abstract should describe the disclosure sufficiently to assist readers in deciding whether there is a need for consulting the full patent text for details.

The language should be clear and concise and should not repeat information given in the title. It should avoid using phrases which can be implied, such as, "The disclosure concerns," "The disclosure defined by this invention," "The disclosure describes," etc.

Claim Rejections - 35 USC § 102/103(a)

3. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

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A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

4. Claims 7, 9, and 11 are rejected under 35 U.S.C. 102(b) as being anticipated by Imasu et al. (US 6,208,525, hereinafter, Imasu.)

In regard to claim 7, in fig. 2, Imasu discloses a package substrate, comprising:

a base substrate 2, or rigid board (col. 4, lines 19-20) formed with a plurality of through holes (not numbered), wherein the elements 2C are embedded therein;

a first copper layer 2A, or wiring line, (col. 4, lines 31-32 and lines 38-40) plated predetermined portions of the through holes;

a pattern layer 4C or 4A (col. 4, lines 28-30) formed on the first copper layer; wire bonding pads 22, or lead, (col. 4, line 49) formed on predetermined portions of the pattern layer at an upper surface of the base;

solder ball pads 2B, or electrode pads (col. 4, line 34) formed on predetermined portions of the pattern layer at a lower surface of the base substrate; and

a solder resist 5 and 6, or passivation layer (col. 4, line 45) covering the base substrate and the pattern layer, except for the wire bonding pads and the colder ball pads, the pattern layers, therefore, are formed where there is no resist layer present.

Claims 7, 9, and 11 are rejected under 35 U.S.C. 102(b) as anticipated by or, in the alternative, under 35 U.S.C. 103(a) as obvious over Imasu (mentioned above).

Imasu does not explicitly teach that the copper layers are made by plated, electrolytic Au plating process. However, the limitations " plated, electrolytic Au plating, electroless plated, and serves as a plating lead line " in claims 7-9 and 11 are taken to

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be a product by process limitation, it is the patentability of the claimed product and not of recited process steps which must be established. Therefore, when the prior art discloses a product which reasonably appears to be identical with or only slightly different than the product claimed in a product-by process claim, a rejection based on sections 102 or 103 is fair. A product by process claim directed to the product per se, no matter how actually made, In re Hirao, 190 USPQ 15 at 17 (footnote 3). See In re Fessman, 180 USPQ 324,326(CCPA 1974); In re Marosi et al., 218 USPQ 289,292 (Fed. Cir. 1983); and particularly In re Thorpe, 227 USPQ 964,966 (Fed. Cir. 1985), all of which make it clear that it is the patentability of the final structure of the product "gleaned" from the process steps, which must be determined in a "product by process" claim, and not the patentability of the process. See also MPEP 2113. Moreover, an old or obvious product produced by a new method is not a patentable product, whether claim in "product by process" claim or not.

In regard to claims 8-11, as mentioned above pattern and electrode layers are made of copper, and AU plating is in fact a product by process limitation (see above discussion).

Claim Rejections - 35 USC § 103

5. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

⁽a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

6. Claim 8 is rejected under 35 U.S.C. 103(a) as being unpatentable over Imasu as applied to claims 7, 9, and 11 above, and further in view of lijima et al. (US 2003/0011070, hereinafter, lijima.)

In regard to claims 8, Imasu discloses all of the claimed limitations as mentioned above. Imasu further discloses that some electrical connection elements are made of gold, for example, electrical connection element 15, or bump electrode (col. 8, line 20). Imasu, however, does not expressly disclose the connection pads and wiring pads are made of gold. It should be noted that gold material is widely use for its well known high conductivity and better contact since gold prevent the oxidation from oxygen. For instance, lijima, in fig. 2, discloses an analogous package 20 including a substrate 21 with through hole (section [0035], lines 1-8), wiring layers 25 (section [0035], lines 9-10), pad connections pads 33 formed on top and bottom of the substrate, which made of gold (section [0036], lines 1-4) in order to have a better electrical contact between devices and prevent the pads from oxidation.

Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention was made to substitute gold material for the pad connections as taught by lijima in Imasu's invention in order to prove electrical contact since gold has high conductivity constant and prevent damage from oxidation.

In regard to the limitation "plated", as addressed above, this is a product by process limitation. Please above discussion regarding to claims 7, 9, and 11, wherein the product by process limitations are clearly addressed.

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7. Claim 10 is rejected under 35 U.S.C. 103(a) as being unpatentable over Imasu as applied to claims 7, 9 and 11 above.

In regard to claim 10, Imasu discloses all of the claimed limitation as mentioned above, except the thickness of the plated layer having a thickness of 0.5 to 1.5 um.

At the time of the invention was made, it would have been obvious to a person of ordinary skill in the art to modify the thickness of the above layer because applicant has not disclosed that thickness provides an advantage, is used for a particular purpose, or solves a stated problem. One of ordinary skill in the art, furthermore, would have expected applicant's invention to perform equally well with either shape because they perform the same function of connecting the module through the substrate to the solder balls electrically.

Therefore, it would have been obvious to one of ordinary skill in the art to modify lmasu to obtain the invention as specify in the above claim.

Indeed, it has been held that mere dimensional limitations are prima facie obvious absent a disclosure that the limitations are for a particular unobvious purpose, produce an unexpected result, or are otherwise critical. See, for example, In re Rose, 220 F.2d 459, 105 USPQ 237 (CCPA 1955); In re Rinehart, 531 F.2d 1048, 189 USPQ 143 (CCPA 1976); Gardner v. TEC Systems, Inc., 725 F.2d 1338, 220 USPQ 777 (Fed. Cir. 1984), cert. denied, 469 U.S. 830, 225 USPQ 232 (1984); In re Dailey, 357 F.2d 669, 149 USPQ 47 (CCPA 1966).

Note that the specification contains no disclosure of either the critical nature of the claimed dimensions of any unexpected results arising therefrom. Where

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patentability is aid to be based upon particular chosen dimensions or upon another variable recited in a claim, the Applicant must show that the chosen dimensions are critical. In re Woodruff, 919 F.2d 1575, 1578, 16 USPQ2d 1934, 1936 (Fed. Cir. 1990).

Conclusion

8. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Nathan W. Ha whose telephone number is (571) 272-1707. The examiner can normally be reached on M-TH 8:00-7:00(EST).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy can be reached on (571) 272-1705. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR.

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Nathan Ha

December 15, 2004